Epoxy Flooring System for – Electronic Assembly Areas

By Ressichem Private Limited

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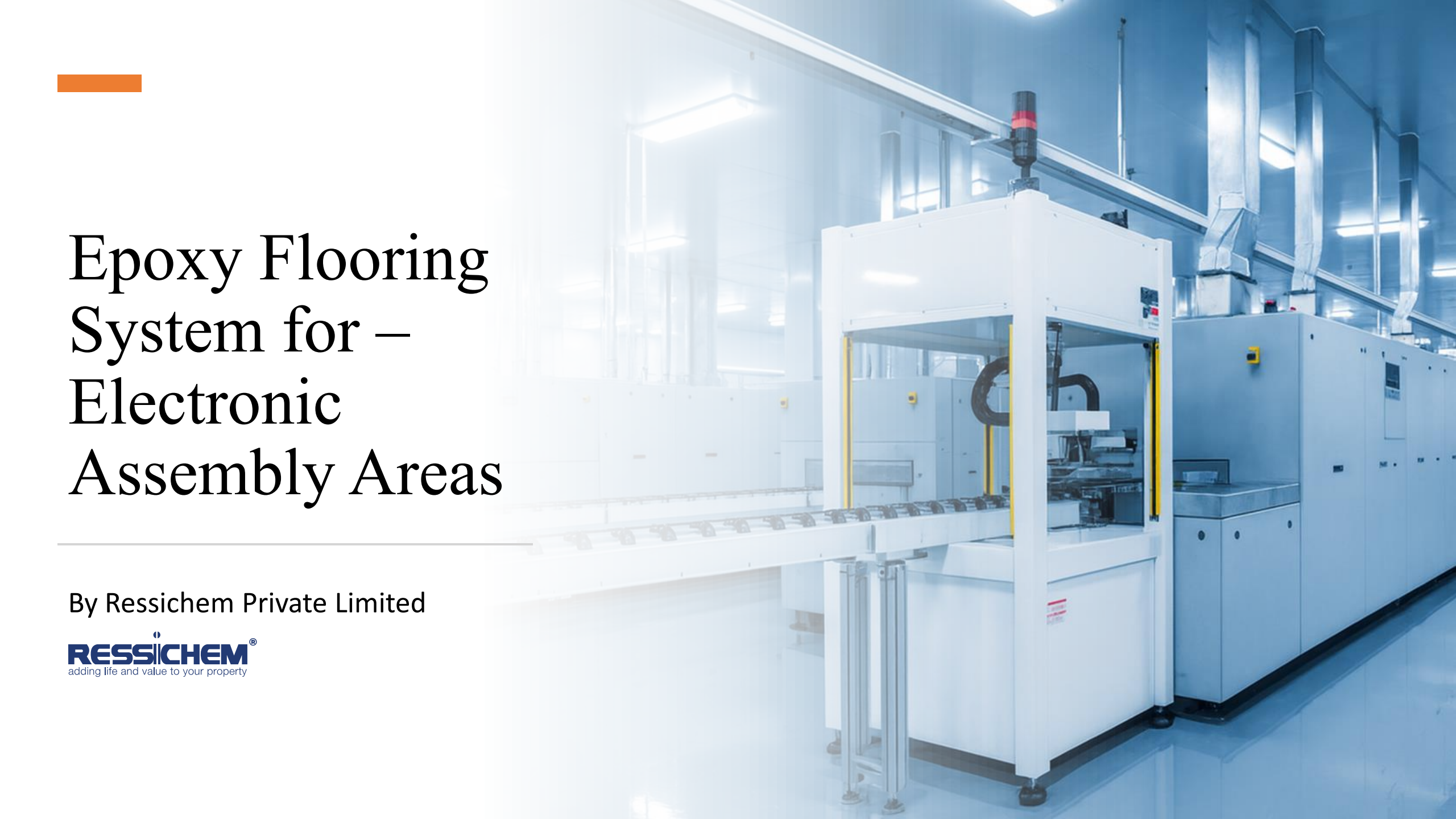


Why Epoxy Floorings at Electronic Assembly Areas

Electronic assembly areas demand a flooring system that ensures **anti-static control, cleanliness, and visual organization**. The surface must help prevent electrostatic discharge (ESD), maintain a smooth, dust-free environment, and enhance workflow precision through defined floor markings.

The **Epoxy Flooring System for – Electronic Assembly Areas** is a **medium-duty, mild anti-static system** developed by Ressichem to deliver **consistent electrostatic performance, durability, and aesthetic precision**. It offers a professional, easy-to-clean finish ideal for modern electronics manufacturing, testing, and assembly facilities.

Recommended Use Cases

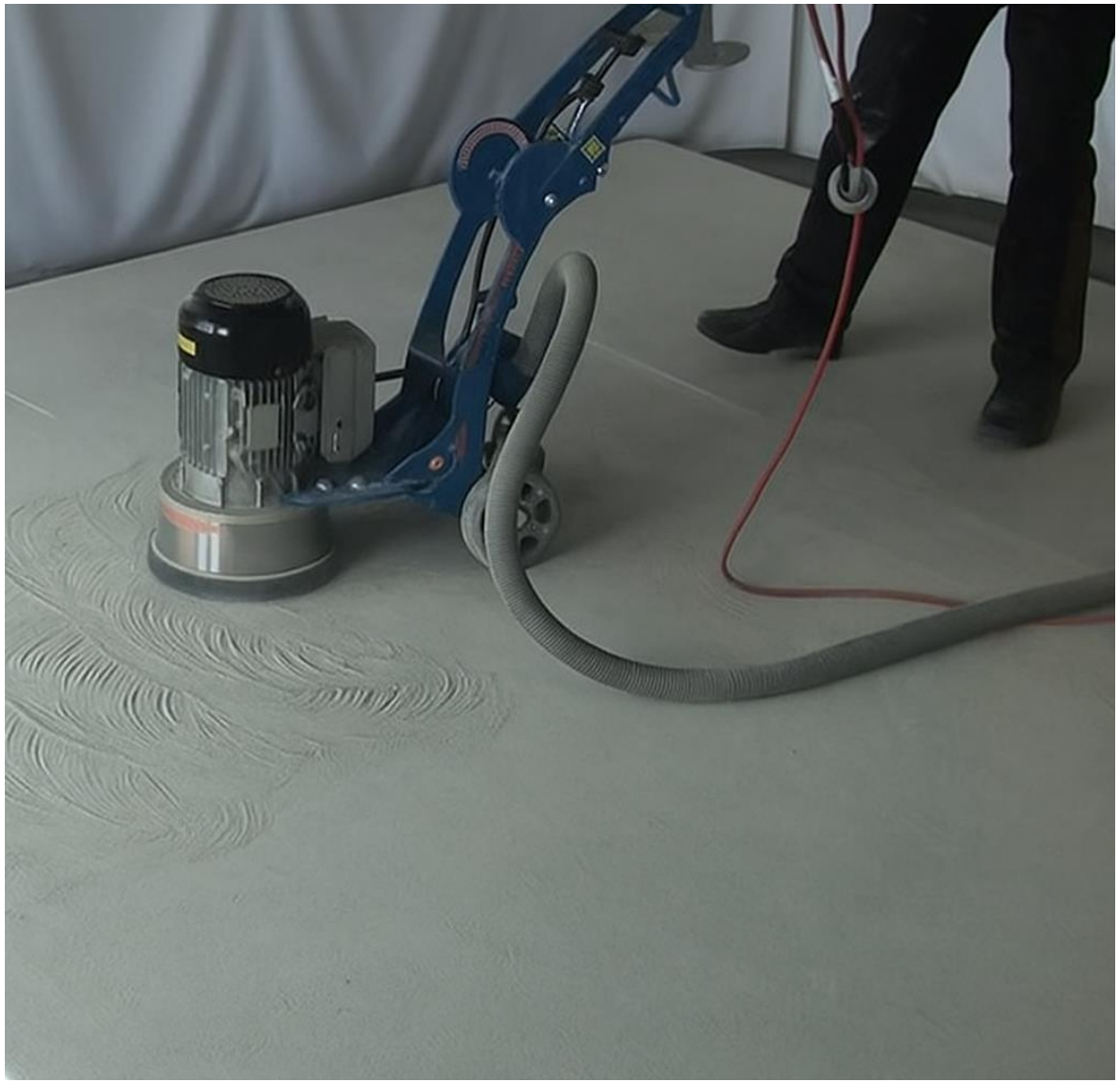
- Electronic component and device assembly areas
- PCB production and testing facilities
- IT rooms, data centers, and server zones
- Control and instrumentation rooms
- Device calibration and packaging areas
- Cleanroom and ESD-sensitive manufacturing spaces

Step 1: Surface Preparation

Proper substrate preparation is critical for the adhesion and performance of the anti-static system.

All necessary surface repairs, including crack filling or substrate restoration, must be completed prior to the application of any epoxy flooring materials. Ressichem offers a range of suitable crack fillers and repair compounds, including non-shrink cementitious grouts, specifically designed for surface preparation and repair.

- Ensure the concrete substrate is **clean, dry, and free of contaminants** such as oil, laitance, or dust.
- Mechanically grind or shot-blast the surface to remove weak layers.
- Vacuum thoroughly to ensure a completely dust-free substrate.
- Verify that **substrate moisture is below 5 %** before primer application.



Step 2: Application of Ressi EPO Primer LV

Apply **Ressi EPO Primer LV**, a low-viscosity, solvent-free epoxy primer formulated to penetrate the substrate and enhance bonding between layers.

- Mix resin and hardener in the recommended ratio.
- Apply uniformly using a roller or brush.
- Ensure complete coverage without puddling.
- Allow curing as per ambient temperature before the next step.

Step 3: Application of Ressi EPO Mid Coat S – GP *(Optional)*

Apply **Ressi EPO Mid Coat S – GP** when additional surface levelling or mechanical reinforcement is needed.

- Apply at a **minimum thickness of 1000 microns**; **2000 microns** are recommended for high-precision, smooth surfaces.
- Spread evenly with a notched trowel or squeegee, followed by back-rolling.
- Allow to cure overnight before the topcoat application.
- This step is **optional**, depending on substrate conditions and levelling requirements.

Step 4: Application of Final Anti-Static Topcoat

Apply **Ressi EPO Anti-Static**, a conductive epoxy coating formulated to safely dissipate electrostatic charges while maintaining a seamless and cleanable surface.

- If **Ressi EPO Mid Coat S – GP** is used → apply **Ressi EPO Anti-Static at 1000 microns**.
- If **no mid coat** is used → apply **Ressi EPO Anti-Static at 2000 microns** to ensure total system thickness.
- Mix resin and hardener as specified and apply using a roller or squeegee for a smooth, uniform finish.
- Allow **48–72 hours** for mild traffic and **7 days** for full cure.

Step 5: Floor Markings *(If Required)*

Apply **Ressi EPO Gloss Might** in a contrasting color as a **roller-applied coat** to mark designated workflow or safety zones.

- Ensure the base surface is cured and clean before applying markings.
- Use masking tape to maintain sharp boundaries.
- Allow complete curing before reopening the area.

Note:

- The **total system thickness must be a minimum of 2000 microns.**
- The **Ressi EPO Mid Coat S – GP** layer is optional, depending on floor condition and levelling needs.
- Refer to the **product Technical Datasheets (TDS)** for details regarding **mixing ratios, coverage, pot life, and environmental conditions** prior to installation.

System Summary Table

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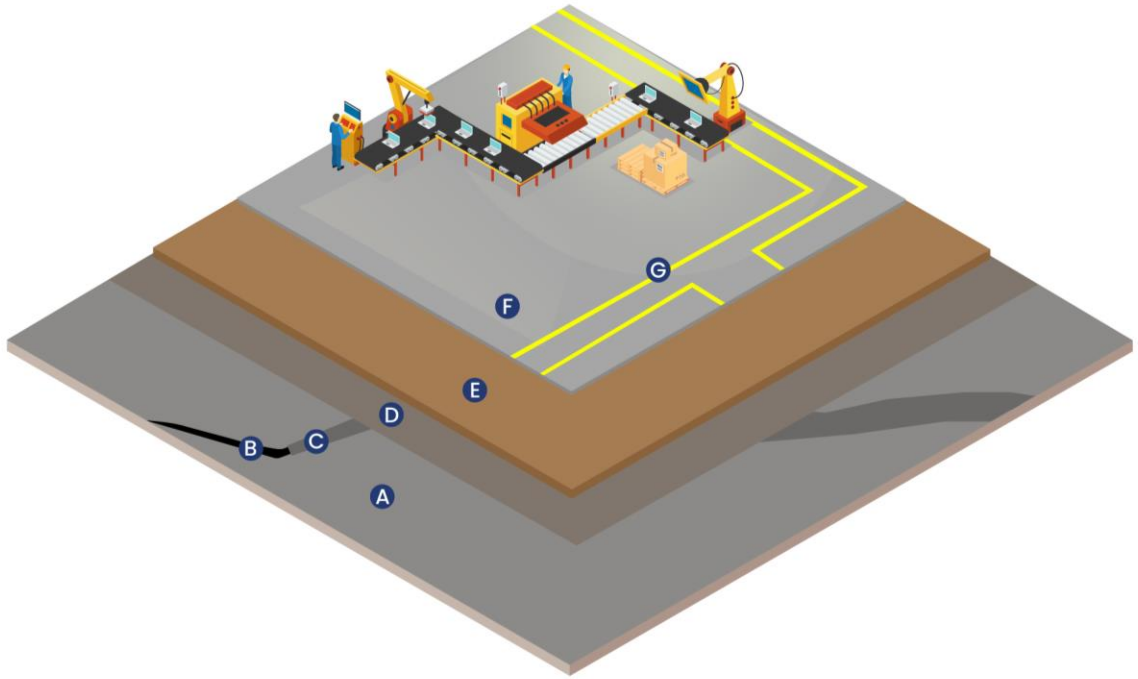
Parameter	Description
System Name	Epoxy Flooring System for – Electronic Assembly Areas
Area Type	Electronic Production, Assembly, and IT Environments
Traffic Exposure	Light to Medium Duty
Primary Requirements	Anti-Static Control, Smoothness, Hygiene, Workflow Organization
Primer	Ressi EPO Primer LV
Mid Coat (Optional)	Ressi EPO Mid Coat S – GP (1000–2000 microns)
Topcoat	Ressi EPO Anti-Static (1000 microns with Mid Coat / 2000 microns without Mid Coat)
Marking Coat (Optional)	Ressi EPO Gloss Might (Roller Applied, Alternate Color)
Total System Thickness	Minimum 2000 Microns
Finish Type	Smooth, Gloss
Curing Time Before Use	48–72 Hours for Mild Traffic / 7 Days Full Cure
Key Benefits	Anti-Static Control, Seamless Finish, Cleanability, Durability, Organized Appearance

System Diagram

A) Cementitious Surface: (Concrete slab or screed)
B) Cracks and surface damage
C) Crack Filler and Repairing Materials
D) Ressi EPO Primer LV
E) Ressi EPO Mid Coat S – GP
F) Ressi EPO Anti Static
G) Ressi EPO Gloss Might



Thank You

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